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Claim ³⁵ ~~3~~ (currently amended): The sensing ~~sensor~~ device of ~~claim 30~~ ² ~~claim 1~~

wherein said fixed electrode is ~~formed as~~ a conductive layer on said substrate.

Claim ³ ~~4~~ (currently amended): The sensing ~~sensor~~ device of claim 1 wherein

said sensor comprises ~~is at least partially formed of~~ a cap layer on said substrate.

Claim ⁴ ~~5~~ (currently amended): The sensing ~~sensor~~ device of claim ³ ~~4~~ wherein

said cap layer includes portions defining a diaphragm of said sensor.

Claim ⁵ ~~6~~ (currently amended): The sensing ~~sensor~~ device of claim ³ ~~4~~ wherein

said active circuitry is integrally fabricated in said substrate. ~~with said sensor.~~

Claim ⁶ ~~7~~ (currently amended): The sensing ~~sensor~~ device of claim ³ ~~4~~ wherein

said cap layer is formed of monocrystalline silicon.

Claim ⁷ ~~8~~ (currently amended): The sensing ~~sensor~~ device of claim ³ ~~4~~ wherein

said cap layer is boron doped silicon.

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Claim ⁸ ~~9~~ (currently amended): The sensing ~~sensor~~ device of ~~claim 30~~ ² ~~claim 1~~

wherein said fixed and moveable electrodes define an interior volume therebetween and a

surface cavity in ~~portion of~~ said substrate defines ~~define~~ a displacement cavity in
communication with said interior volume.

⁹
Claim ~~10~~ (currently amended): The sensing ~~sensor~~ device of ~~claim 10~~ ² claim 1
wherein said fixed electrode includes a main electrode and at least one reference electrode.

¹⁰
Claim ~~11~~ (currently amended) The sensing ~~sensor~~ device of claim 1 wherein
said sensing device is entirely implanted within said human body and is operating to measure
the physiologic parameter within said human body. ~~monolithic.~~

¹¹
Claim ~~12~~ (currently amended): The sensing ~~sensor~~ device of claim 1 further
comprising a cap layer formed over said substrate.

¹²
Claim ~~13~~ (currently amended): The sensing ~~sensor~~ device of claim ~~12~~ ¹¹ wherein
said cap layer includes a portion defining a moveable electrode of said sensor.

¹³
Claim ~~14~~ (currently amended): The sensing ~~sensor~~ device of claim ~~13~~ ¹¹ wherein
said cap layer is conductive.

¹⁴
Claim ~~15~~ (currently amended): The sensing ~~sensor~~ device of claim ~~14~~ ¹¹ wherein

32
Claim ~~32~~ (currently amended): The sensing ~~sensor~~ device of claim ~~32~~³¹ wherein
said housing is of a non-rigid material.

33
Claim ~~33~~ (currently amended): The sensing ~~sensor~~ device of claim ~~32~~³¹ wherein
said housing is a plastic material. ~~of plastic.~~

34
Claim ~~34~~ (currently amended): The sensing ~~sensor~~ device of claim ~~32~~³¹ wherein
said housing comprises a recess providing intimate access to the sensor. ~~is soft.~~

m
2 ~~35~~
Claim ~~35~~ (new): The sensing device of claim 1 wherein said sensor is a
capacitive sensor having a fixed electrode and a moveable electrode.